

## **60V N-Channel MOSFET**

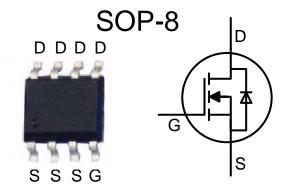
#### **General Features**

- ➤ Fast Switching Speed
- > RoHS Compliant
- ➤ Halogen-free available

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- ➤ Power Management in Inverter System
- > Synchronous Rectification

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> (Typ.)	$I_D$
60V	11m Ω	15A



**Ordering Information** 

Part Number	Package	Marking	Remark
FTE11N06G	SOP-8	11N06G	Halogen Free

## **Absolute Maximum Ratings**

T<sub>A</sub>=25°C unless otherwise specified

Symbol	Paramete	Rating	Unit	
$V_{ m DSS}$	Drain-Source Voltage <sup>[1]</sup>		60	V
$V_{GS}$	Gate –Source Voltage		<u>+25</u>	V
т	Continuous Drain Current	Tc=25 °C	15	A
$I_{D}$	Continuous Drain Current	10	A	
$I_{DP}$	300us Pulsed Drain Current	30	A	
D	Power Dissipation	5.2	W	
P <sub>D</sub> Derating Factor above 25 °C			0.04	<b>W</b> /°C
$T_{\text{J}}$ and $T_{\text{STG}}$	Operating and Storage Temp	erature Range	-55 ~ 150	${\mathcal C}$

<sup>\*</sup>Drain Current limited by Maximum Junction Temperature.

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.

## **Thermal Characteristics**

Symbol	Parameter	Rating	Unit
$R_{ heta JC}$	Thermal Resistance, Junction-to-Case	24	°C/W
$R_{ heta JA}$	Thermal Resistance, Junction-to-Ambient	85	C/W



## **Electrical Characteristics**

## **OFF Characteristics**(TA=25 °C unless otherwise noted)

Symbol	Parameter	Min.	Тур.	Max.	Unit	<b>Test Conditions</b>
$BV_{DSS}$	Drain-Source Breakdown Voltage	60	1	1	V	$V_{GS}$ =0V, $I_{D}$ =250 $\mu$ A
$I_{DSS}$	Zero Gate Voltage Drain Current			1	μΑ	$V_{DS}=48V, V_{GS}=0V,$
Ţ	Cata Laaka ga Currant		-	100	nA	$V_{GS}=20V$ , $V_{DS}=0V$
$I_{GSS}$	Gate Leakage Current			-100	nA	$V_{GS}$ =-20V, $V_{DS}$ =0V

#### **On Characteristics**

Symbol	Parameter	Min.	Тур.	Max.	Unit	<b>Test Conditions</b>
R <sub>DS(ON)</sub> Drain-Source On-Resistance <sup>[3]</sup>	Drain Source On Posistance <sup>[3]</sup>		11	15	mΩ	$V_{GS}=10V, I_{D}=15A$
	Dram-Source On-Resistance		16	18	mΩ	$V_{GS} = 5V, I_D = 10A$
$V_{\text{GS(TH)}}$	Gate Threshold Voltage	2		4	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
GFS	Forward Transconductance				S	$V_{DS}=30V, I_{D}=40A$

#### **Dynamic Characteristics**

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions
$R_{G}$	Gate Resistance		1.2		Ω	$V_{GS}$ =0V, $V_{DS}$ =0V, f=1MHz
C <sub>iss</sub>	Input Capacitance					
C <sub>oss</sub>	Output Capacitance		-	-	pF	$V_{GS}$ =0V, $V_{DS}$ =30V, f=1MHz
$C_{rss}$	Reverse Transfer Capacitance		1	1		
$Q_{g}$	Total Gate Charge					
$Q_{gs}$	Gate-Source Charge				nC	$V_{DS}=30V, V_{GS}=10V, I_{D}=15A$
$Q_{gd}$	Gate-Drain Charge					- J

#### **Resistive Switch Characteristics**

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions
t <sub>d(on)</sub>	Turn-On Delay Time					
t <sub>r</sub>	Turn-On Rise Time					$V_{DD}=30V,R_L=30\Omega$
t <sub>d(off)</sub>	Turn-Off Delay Time				ns	$I_{D}$ =1.0A, $V_{GS}$ =10V $R_{G}$ =6 $\Omega$
$t_{\mathrm{f}}$	Turn-Off Fall Time					



#### **Source-Drain Diode Characteristics**

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions
$I_{\mathrm{SD}}$	Continuous Source Current(Body Diode)			15	A	Integral P-N diode in
$I_{SM}$	Maximum Pulsed Current(Body Diode)			30	A	MOSFET
$V_{\mathrm{SD}}$	Diode Forward Voltage			1.2	V	$I_{SD}=15A, V_{GS}=0V$
t <sub>rr</sub>	Reverse Recovery Time				ns	I <sub>SD</sub> =15A,
Q <sub>rr</sub>	Reverse Recovery Charge				nC	$dI_{SD}/dt=100A/\mu A$

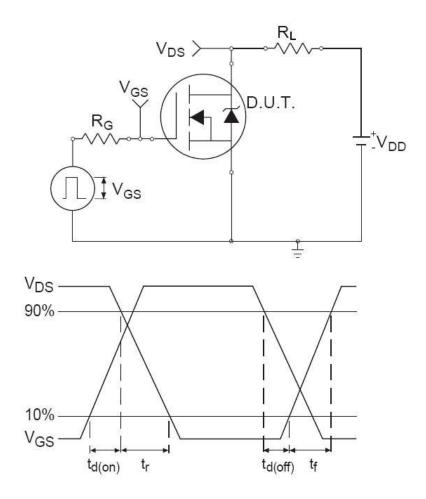
#### NOTE:

<sup>[1]</sup>  $T_J = +25^{\circ}C$  to  $+150^{\circ}C$ 

<sup>[2]</sup> Repetitive rating, pulse width limited by maximum junction temperature. [3] Pulse width \( \frac{380}{\text{ µs}}; \) duty cycle \( \frac{2}{\text{ %}}. \)



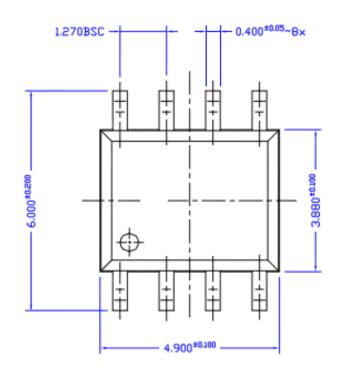
# **Switching Time Test Circuit and Waveforms**

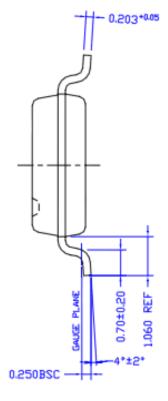


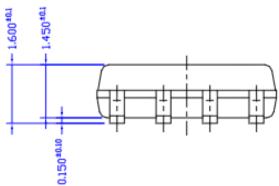


## **Package Dimensions**

## SOP-8









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